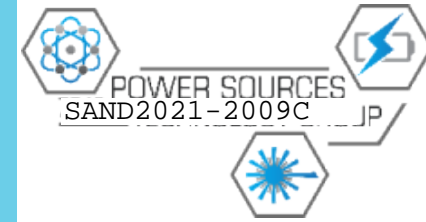




This paper describes objective technical results and analysis. Any subjective views or opinions that might be expressed in the paper do not necessarily represent the views of the U.S. Department of Energy or the United States Government.



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COMPONENT SCIENCE, ENGINEERING, & PRODUCTION



Mitigation of Failure Propagation: A Model-Based Experimental Design

PRESENTED BY

Loraine Torres-Castro

Team members: Chris Grosso, Randy Shurtz, Andrew Kurzawski, Josh Lamb and John Hewson

March 9,
2021



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Capabilities and Infrastructure

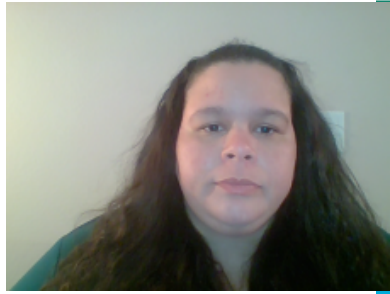
Cell and Module Testing Battery Abuse Testing Laboratory (BATLab)



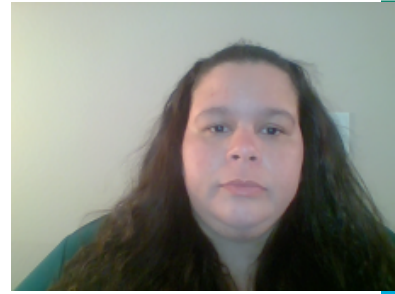
Battery Pack/System Testing Thermal Test Complex (TTC) and Burnsite



Battery Calorimetry



Safety Science



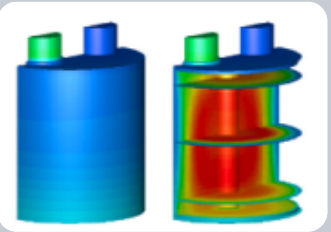
Materials R&D

- Non-flammable electrolytes
- Electrolyte salts
- Coated active materials
- Thermally stable materials



Testing

- Electrical, thermal, mechanical abuse testing
- Battery calorimetry
- Large scale thermal and fire testing (TTC)
- Failure propagation testing on batteries/systems
- Degradation and diagnostics during and post battery failure



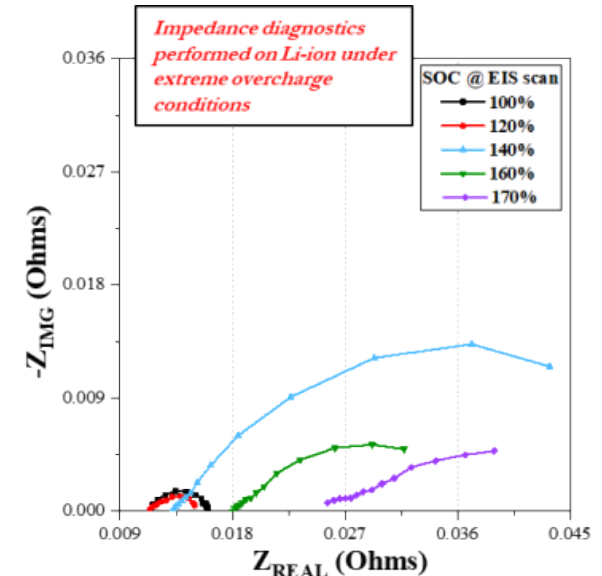
Simulations and Modeling

- Multi-scale models for understanding thermal runaway
- Validating failure propagation models
- Fire Simulations to predict the size, scope, and consequences of battery fires



Procedure Development and Stakeholder Interface

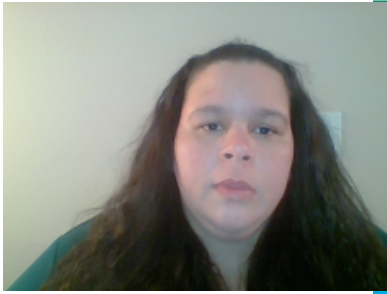
- USABC Abuse Testing Manual (SAND 2005 3123)
- OE Energy Storage Safety Roadmap
- R&D programs with NHTSA/DOT to inform best practices, policies, and requirements



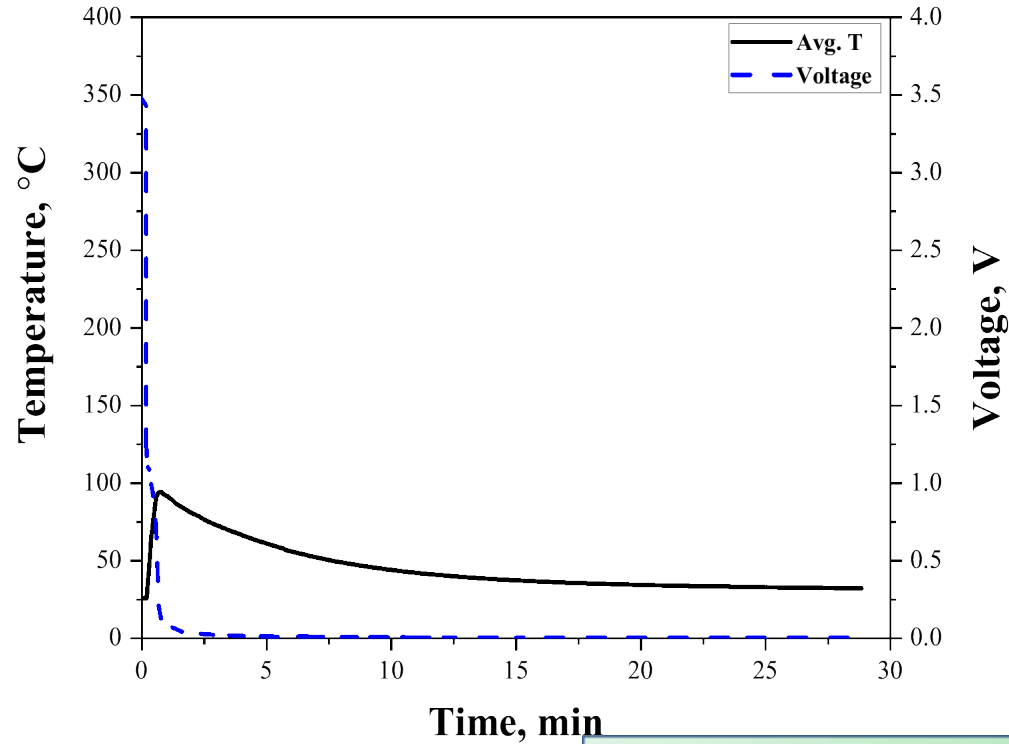
Sandia is uniquely positioned to study the entire life cycle of a technology.

New technologies present new risks. A high rigor environment at Sandia allows those risks to be adequately managed.

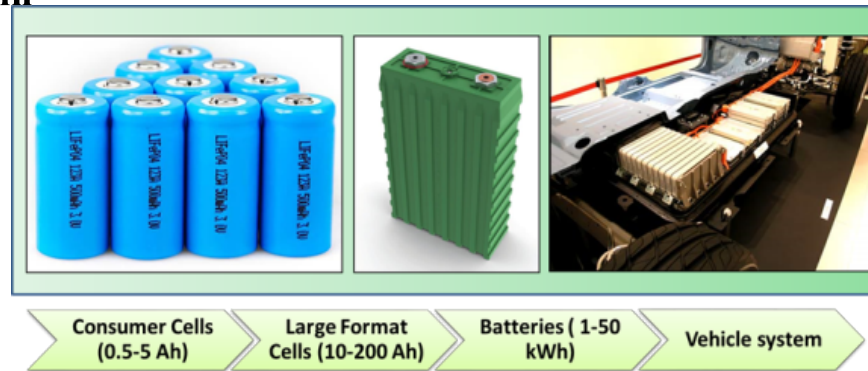
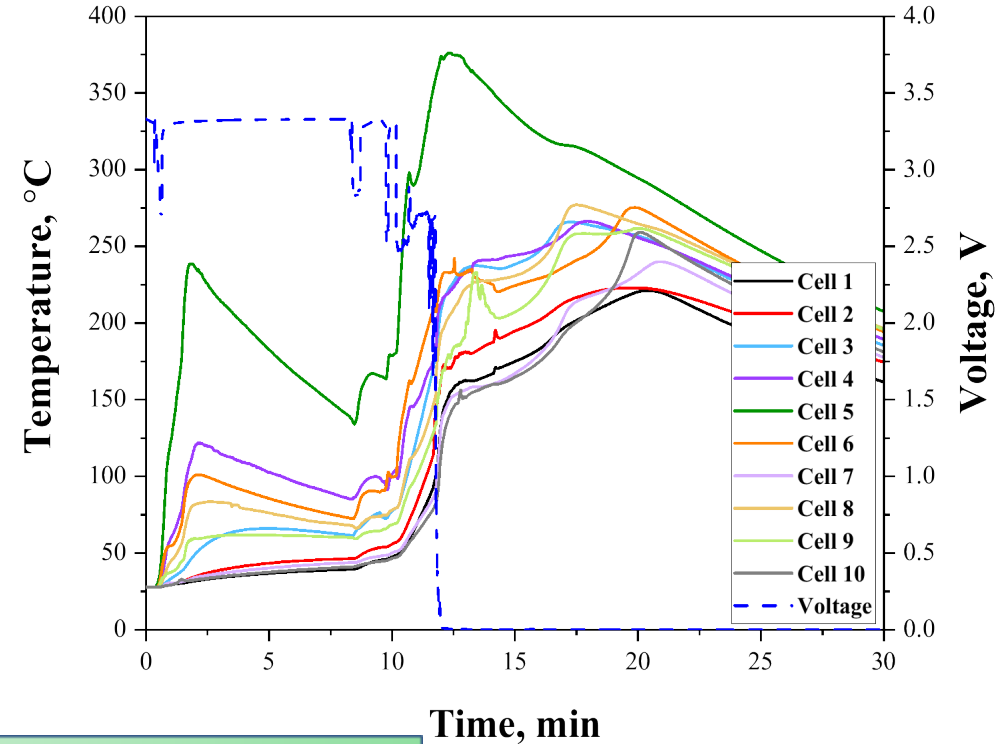
Motivation for Propagation Testing



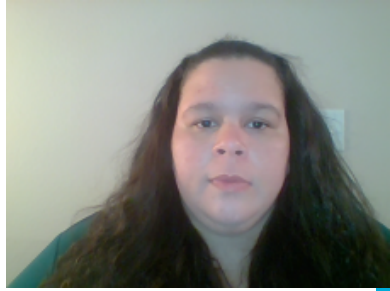
Single Cell Failure



How do these behaviors impact a larger, more complex system?



Strategies to Mitigate Failure Propagation



Passive Mitigation

- Heat dissipation (e.g., heat sink, phase change)
- Inter-cell/inter-module spacing (e.g., triangular configuration of cylindrical cells)
- Reduce available energy (e.g., limited state of charge)

Active Mitigation (external energy input required)

- Air cooling
- Liquid cooling (e.g., water, ethylene glycol)

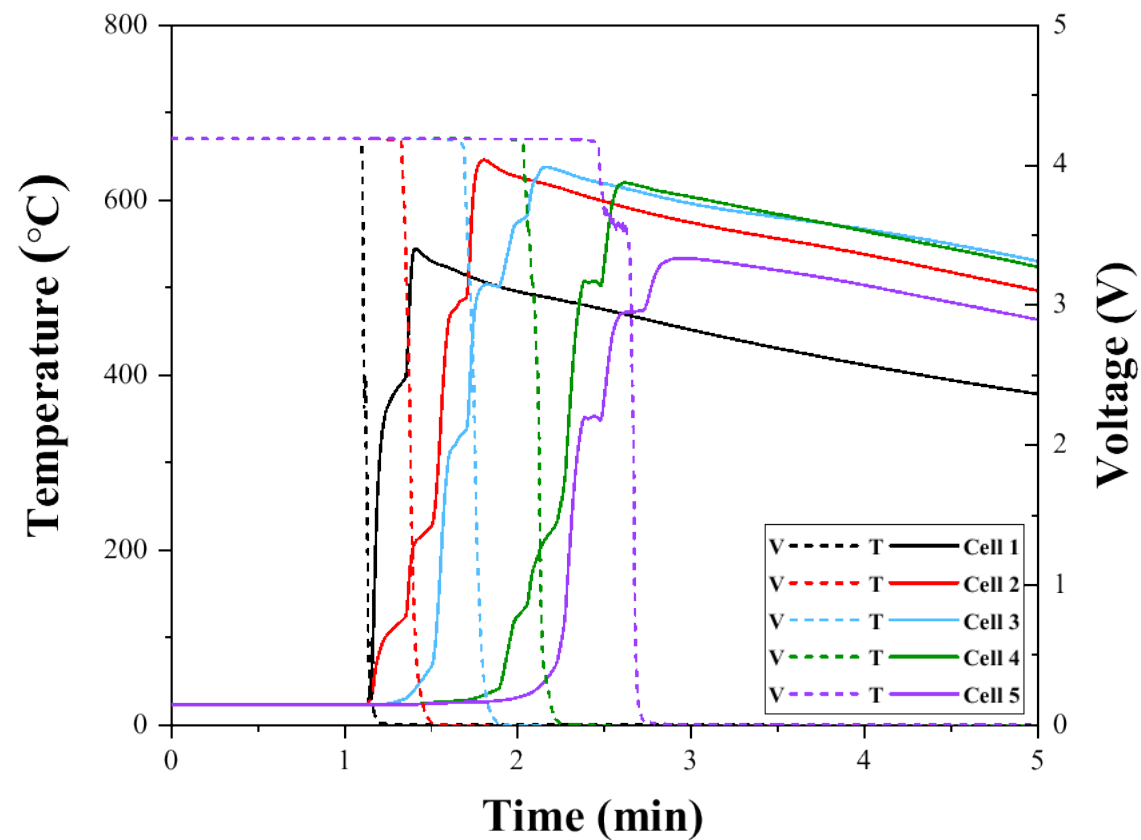
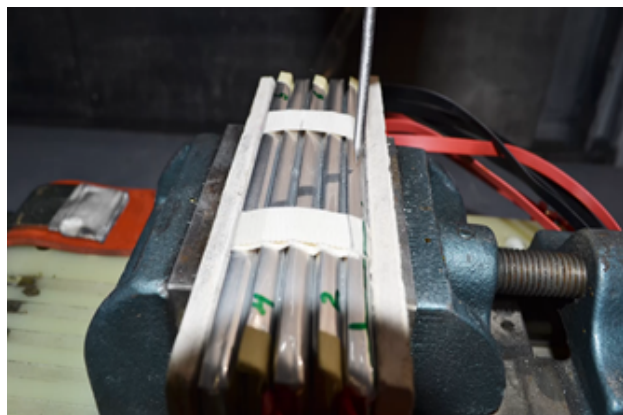
Objective

Reduce the risk of failure propagation with passive and active thermal management

Unmitigated Failure Propagation

Test Details

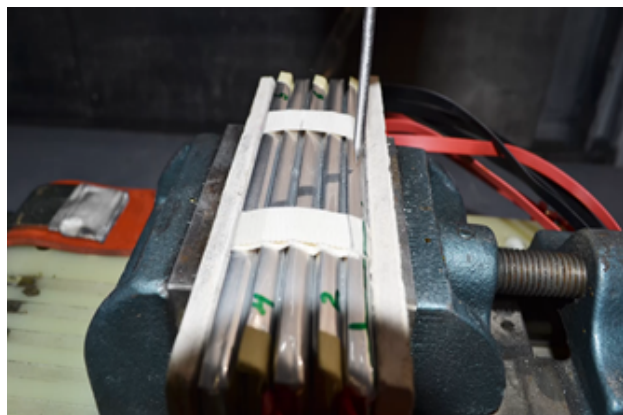
- LiCoO_2 3Ah pouch cells
- 5 closely packed cells
- Failure initiated by a mechanical nail penetration in the outer cell (cell 1)
- Thermocouples (TC) between cells



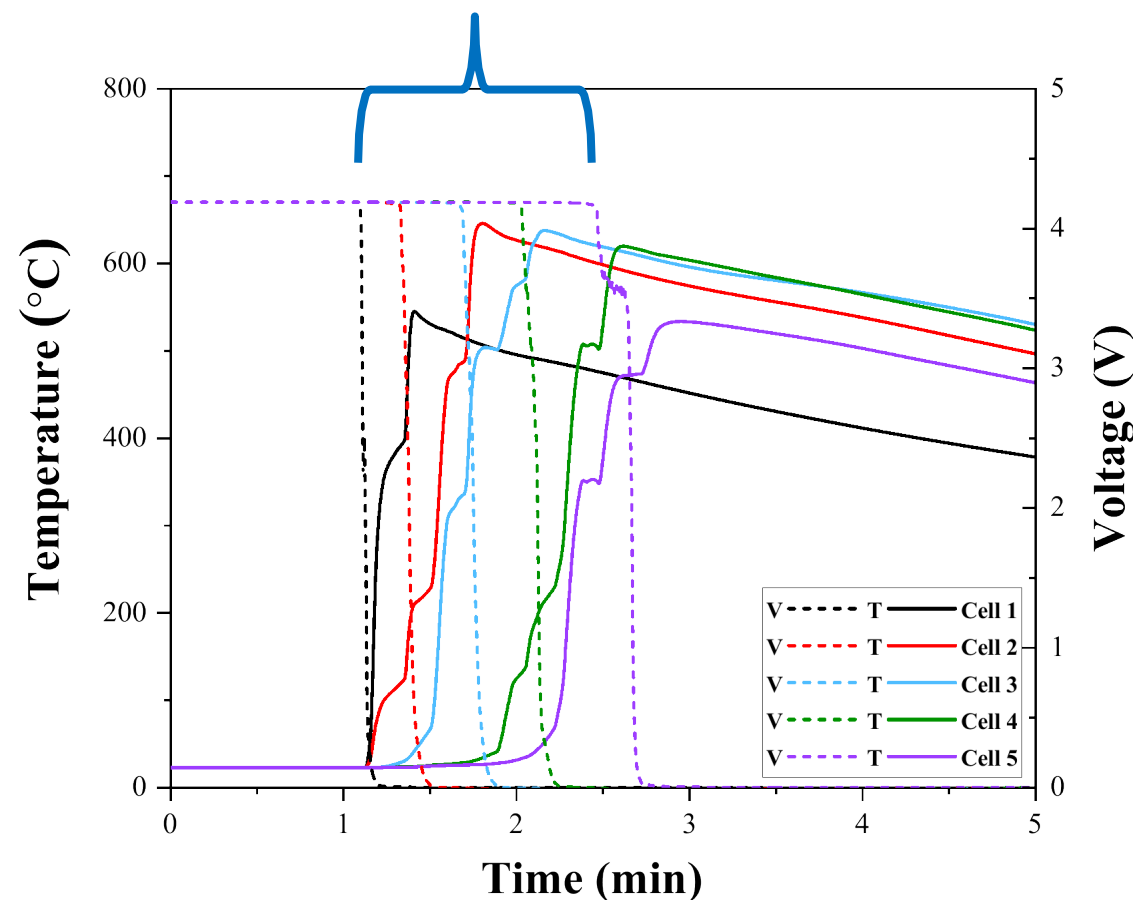
Unmitigated Failure Propagation

Test Details

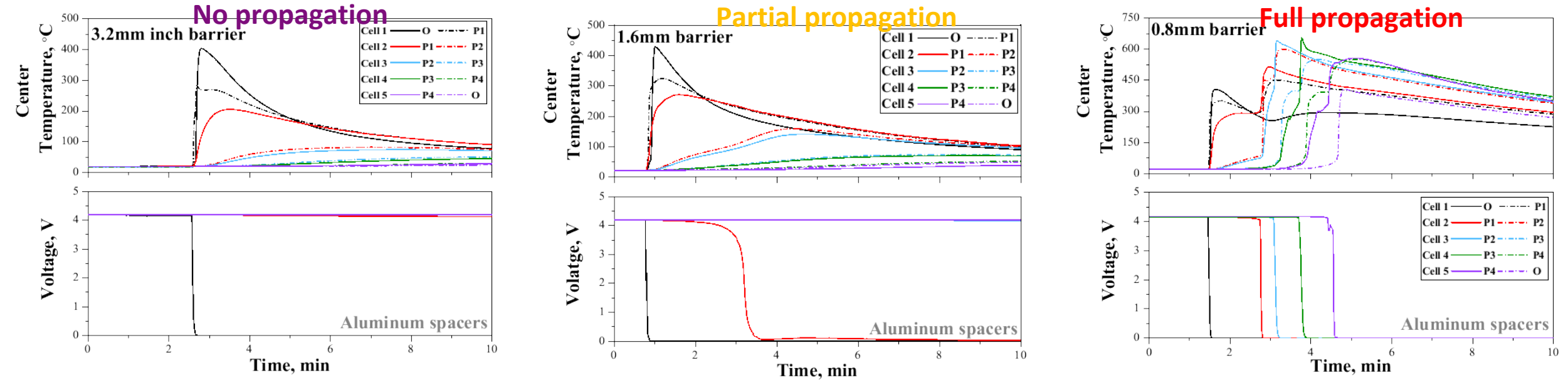
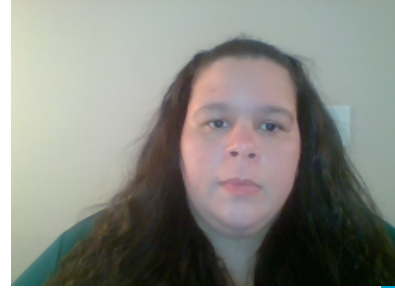
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- Thermocouples (TC) between cells



Cascading failure to entire battery over 82 s



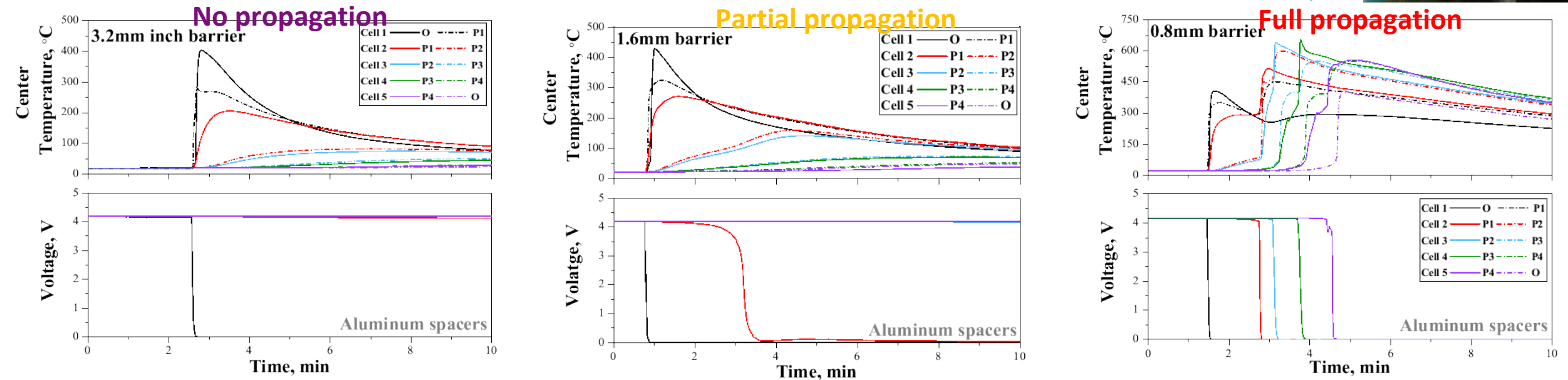
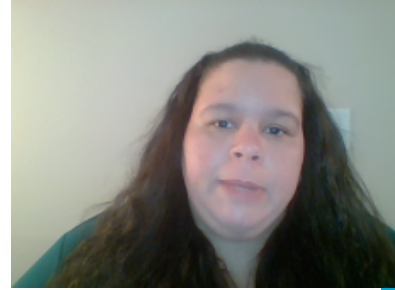
Failure Propagation with Passive Mitigation



- The plates provided an additional thermal mass to dissipate heat release, hence reducing the risk of propagation
- Thinner plates did not prevent failure propagation, but they significantly reduced the overall heat release rate and propagation speed

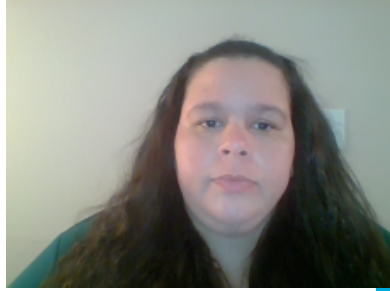
Failure Propagation with Passive Mitigation

Risk of Propagation



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- Thinner plates did not prevent failure propagation, but they significantly reduced the overall heat release rate and propagation speed

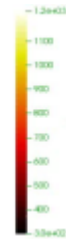
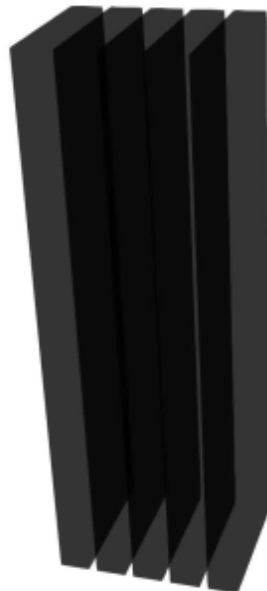
Predicting Thermal Runaway



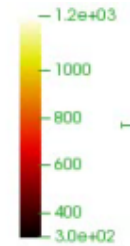
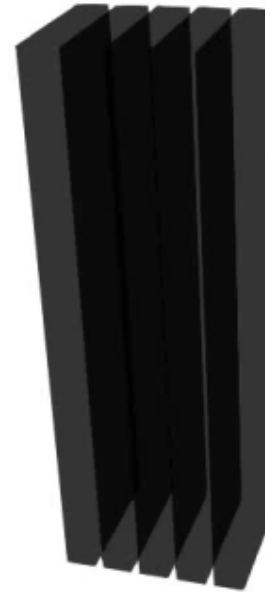
Large-scale testing is costly, and simulations allow exploration of the design space if well grounded in reality



Short circuit
simulated in
first cell acts
as boundary
condition



Baseline
cell stack:
**Thermal
runaway
propagates**

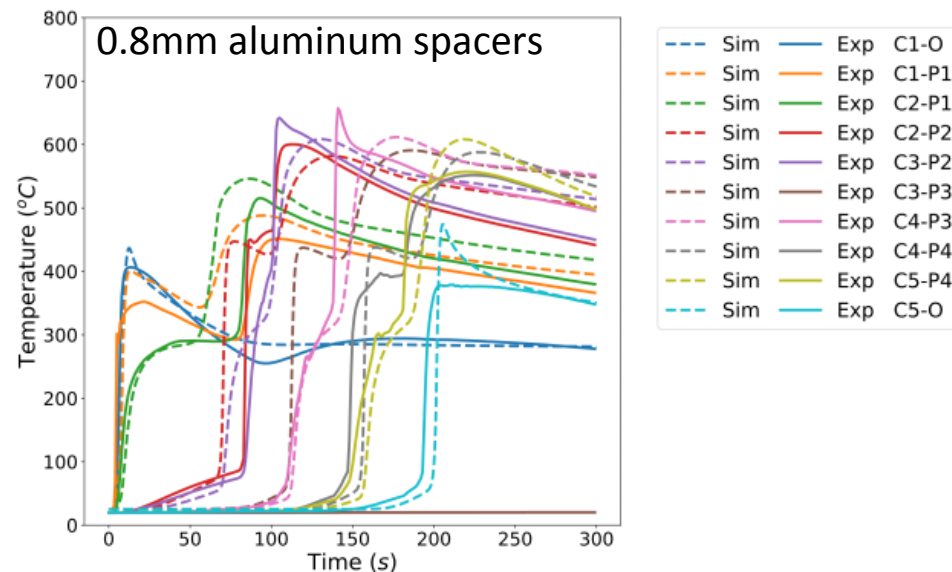
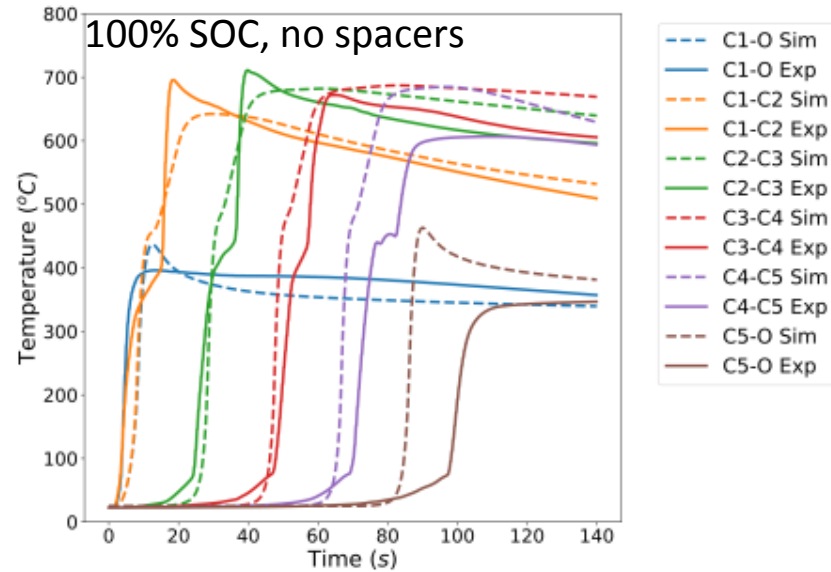
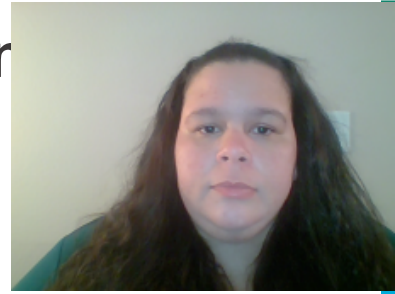


Thermal
modifications
(Reduced
conductivity,
increased
contact
resistance):
**Propagation
mitigated**

- Measurements are reality but simulations allows us to better understand the behavior changes
- Explore boundaries between mitigation and cascading failure

Temperature-Time Propagation Measurements and Prediction

by Andrew Kurzawski

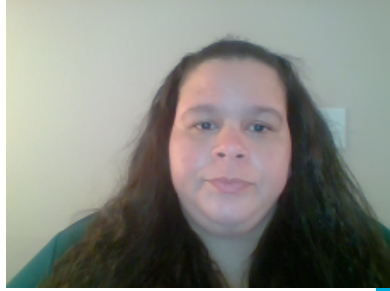


Metallic inserts

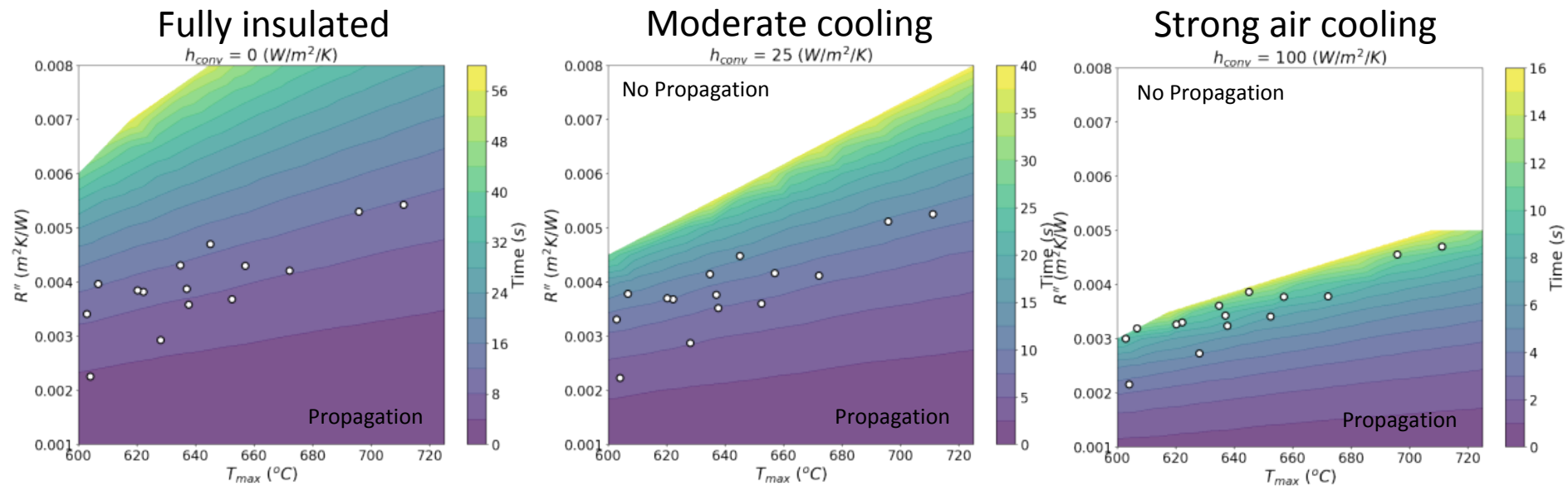
- Add heat capacity
- Increase time delay for cell runaway
- Prevent propagation for 30% increase in net heat capacity
- Reduced SOC results suggest homogeneous heat capacity changes of 25% sufficient

Limits of Failure Propagation

by Andrew Kurzawski



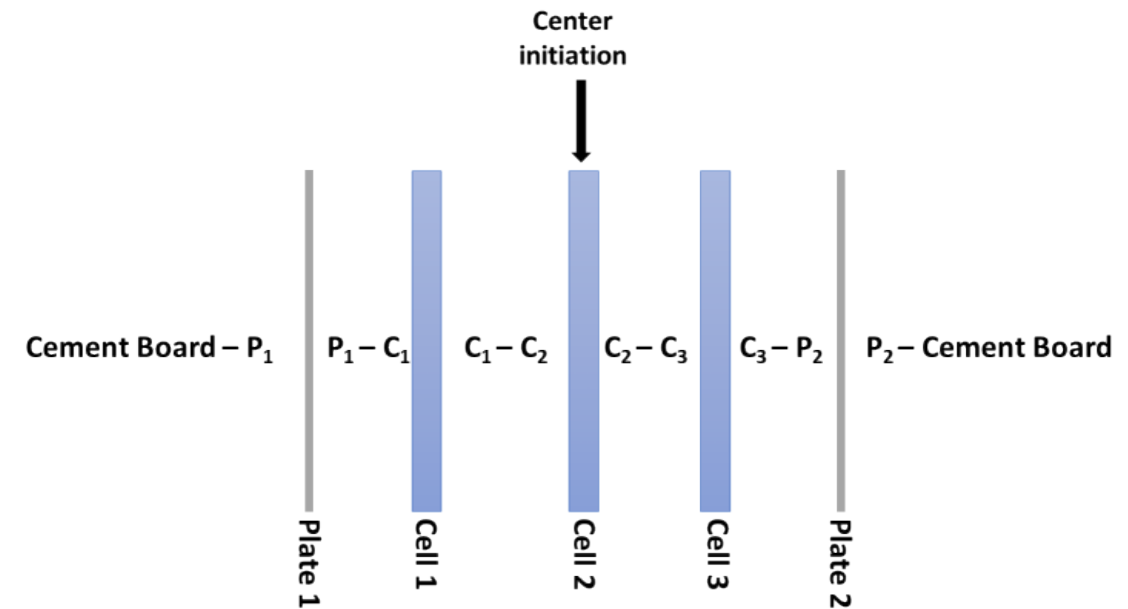
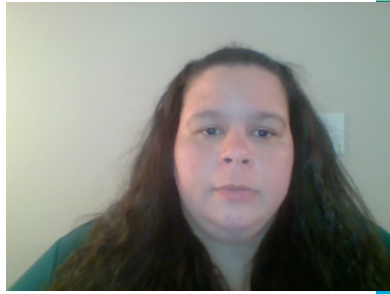
Energy per heat capacity, cooling and inter-cell resistance defines propagation limits
Model maps delay in propagation: yellow region is infinite delay—*failure to propagate*.



Convection cooling and conduction through stack results in failure to propagate for some scenarios.

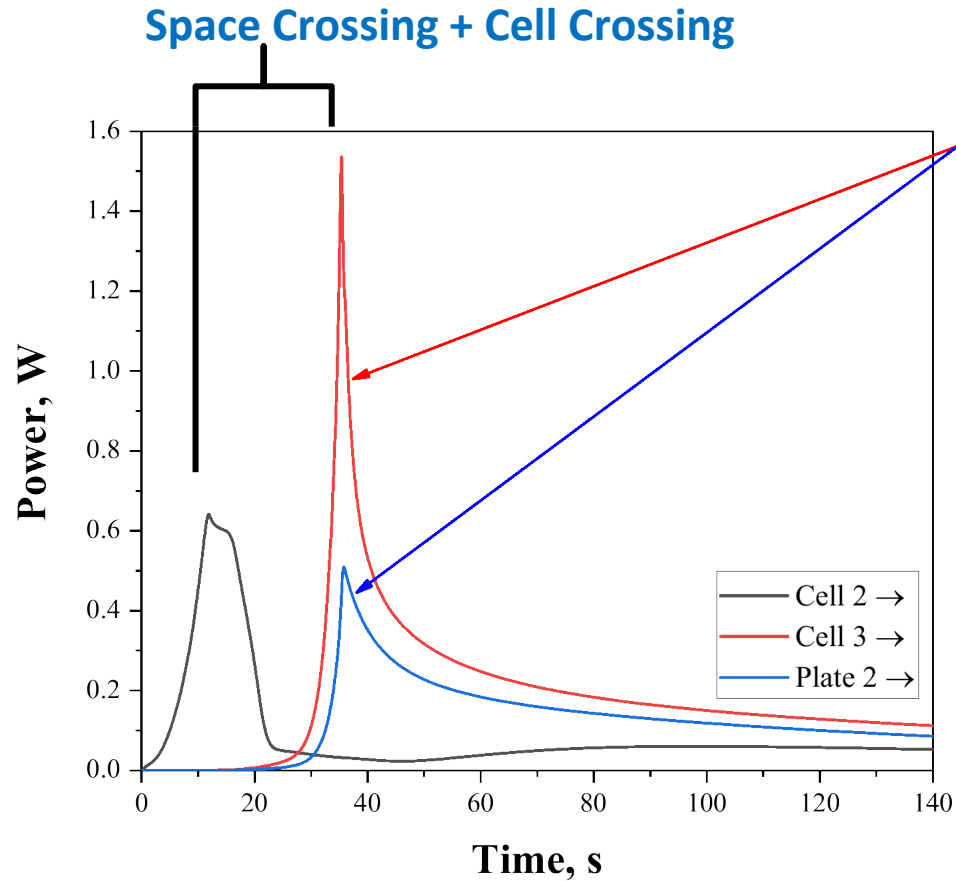
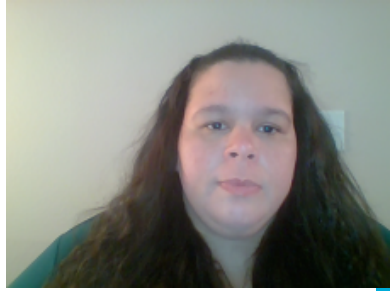
Consider cost/design tradeoff : cooling versus thermal resistance.

Exploration of Mitigation Strategies Through Simulations

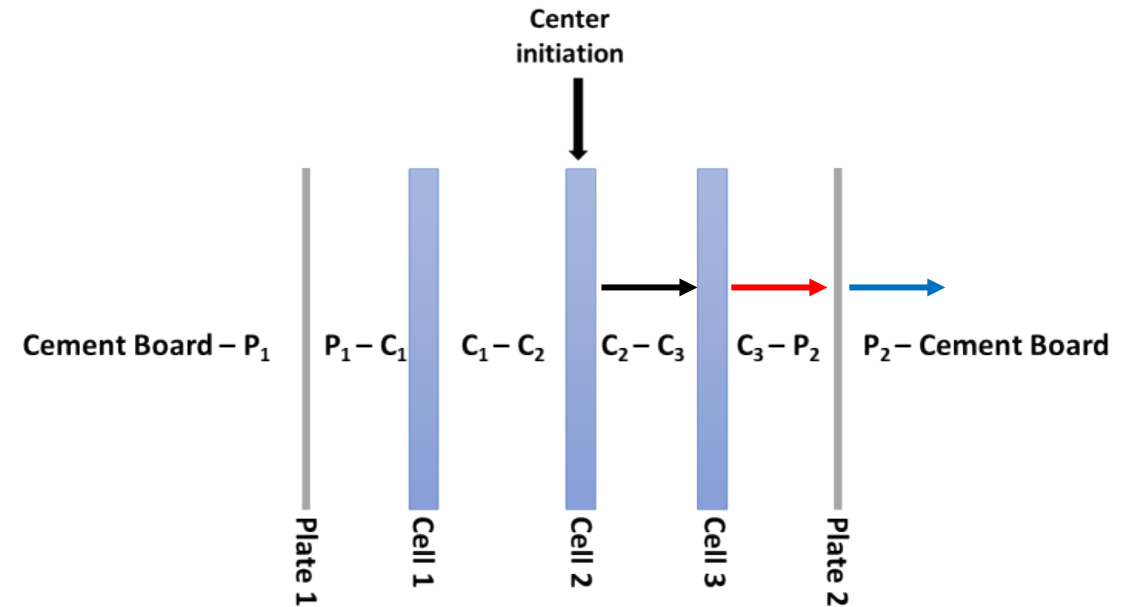


Exploration of Mitigation Strategies Through Simulations

by Randy Shurtz

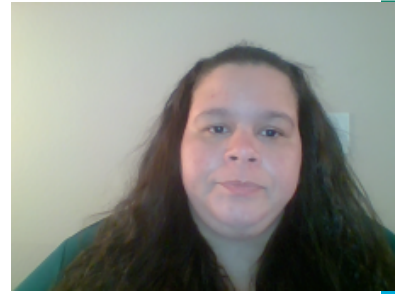


Difference between heat out of last cell and heat out of plate

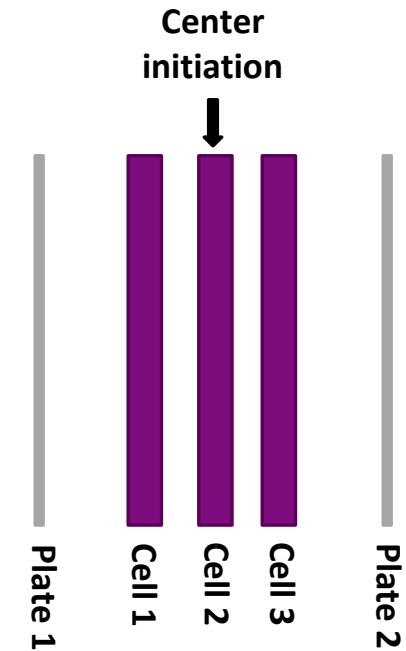
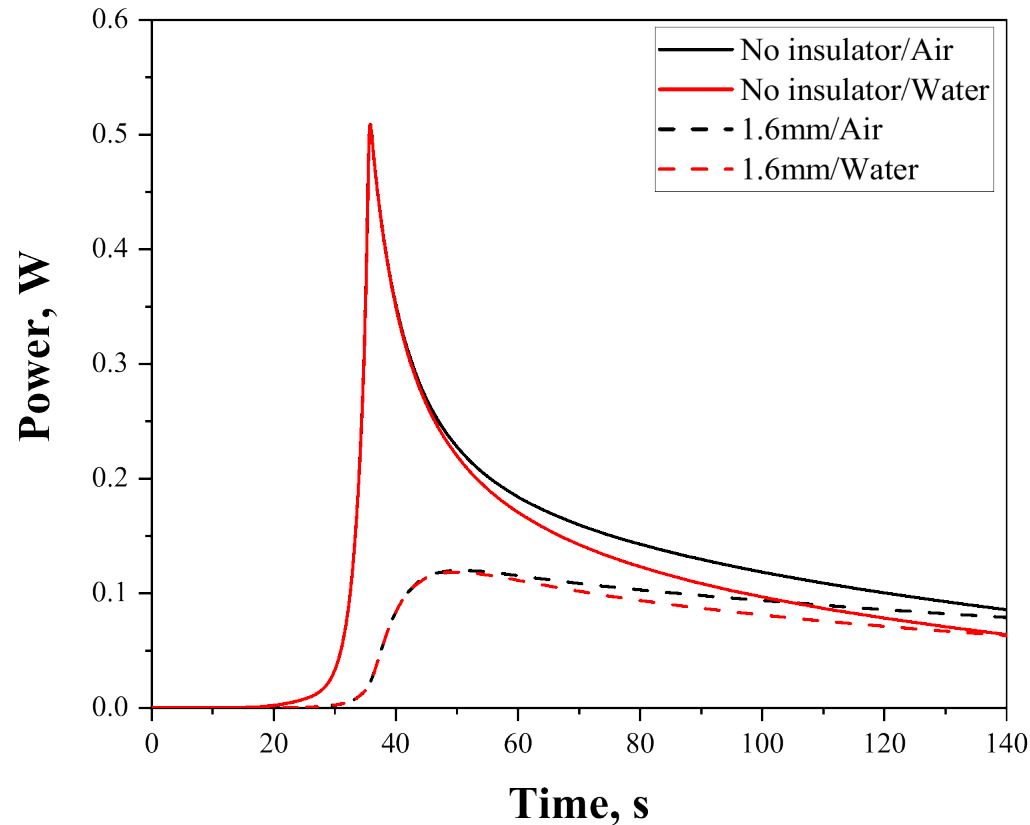


Exploration of Mitigation Strategies Through Simulations

by Randy Shurtz



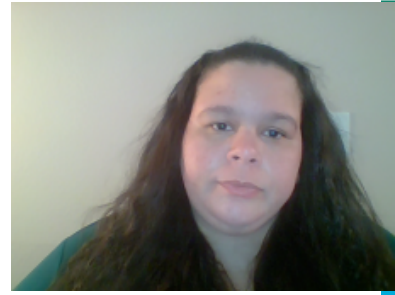
Effect of insulator thickness on the heat out of the battery pack



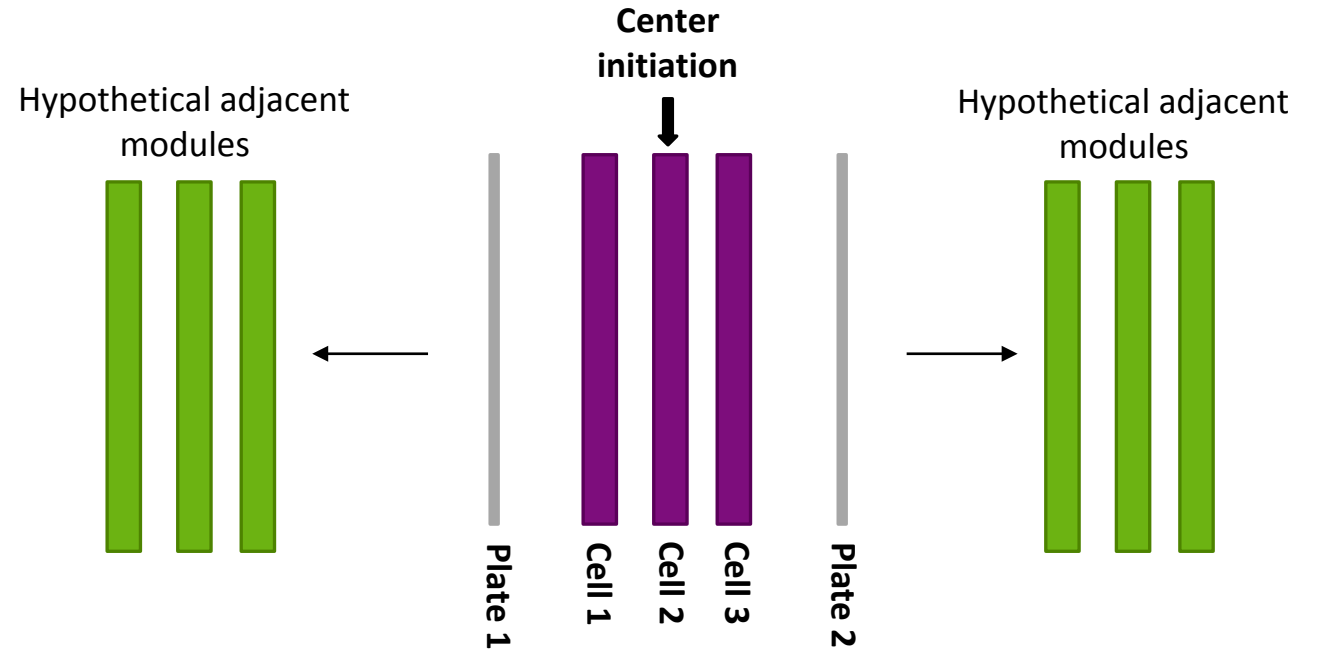
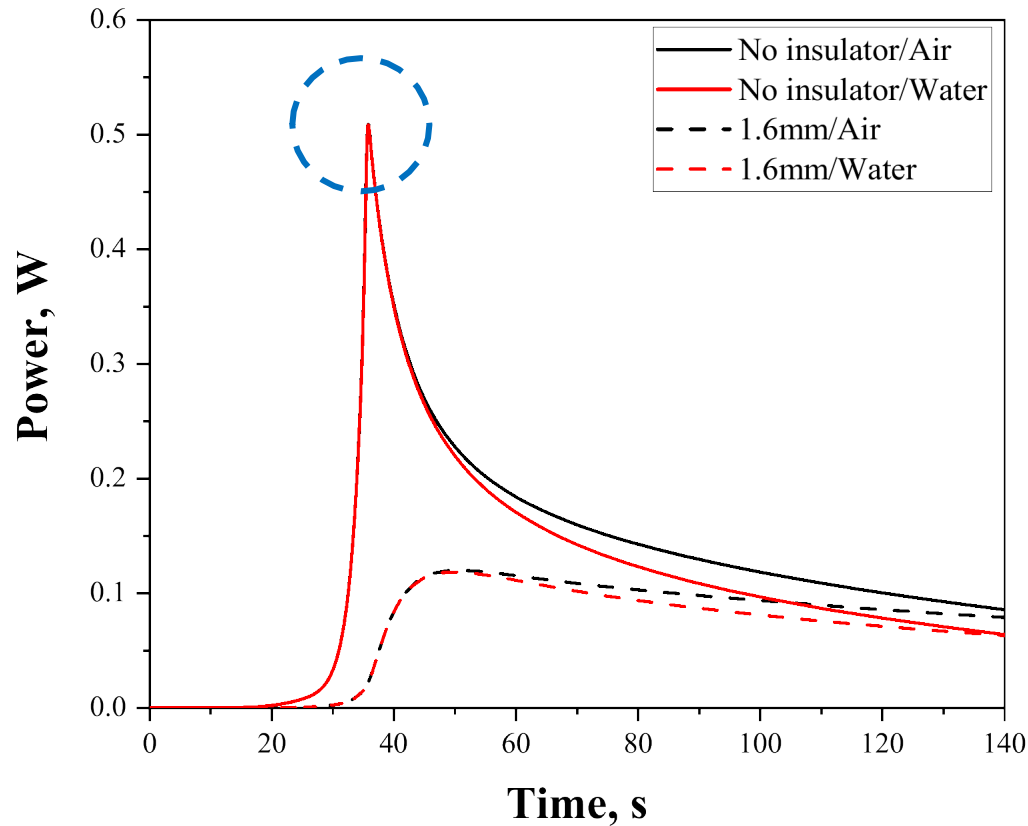
Water cooling increases decay rate of tails, indicating more heat transfer out of the stack

Exploration of Mitigation Strategies Through Simulations

by Randy Shurtz



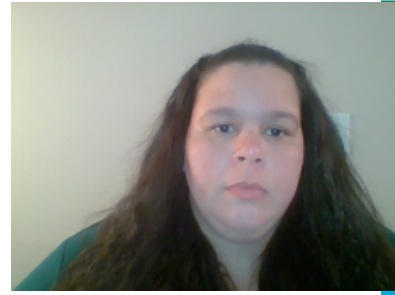
Effect of insulator thickness on the heat out of the battery pack



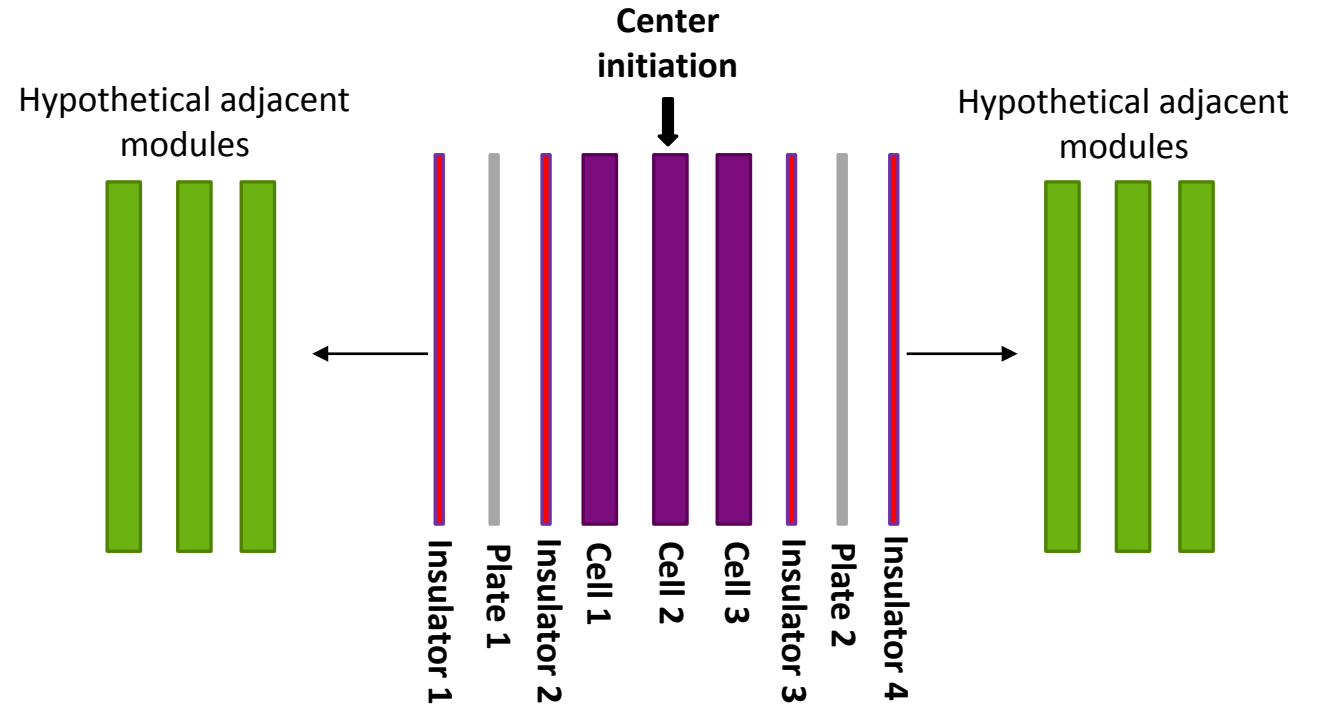
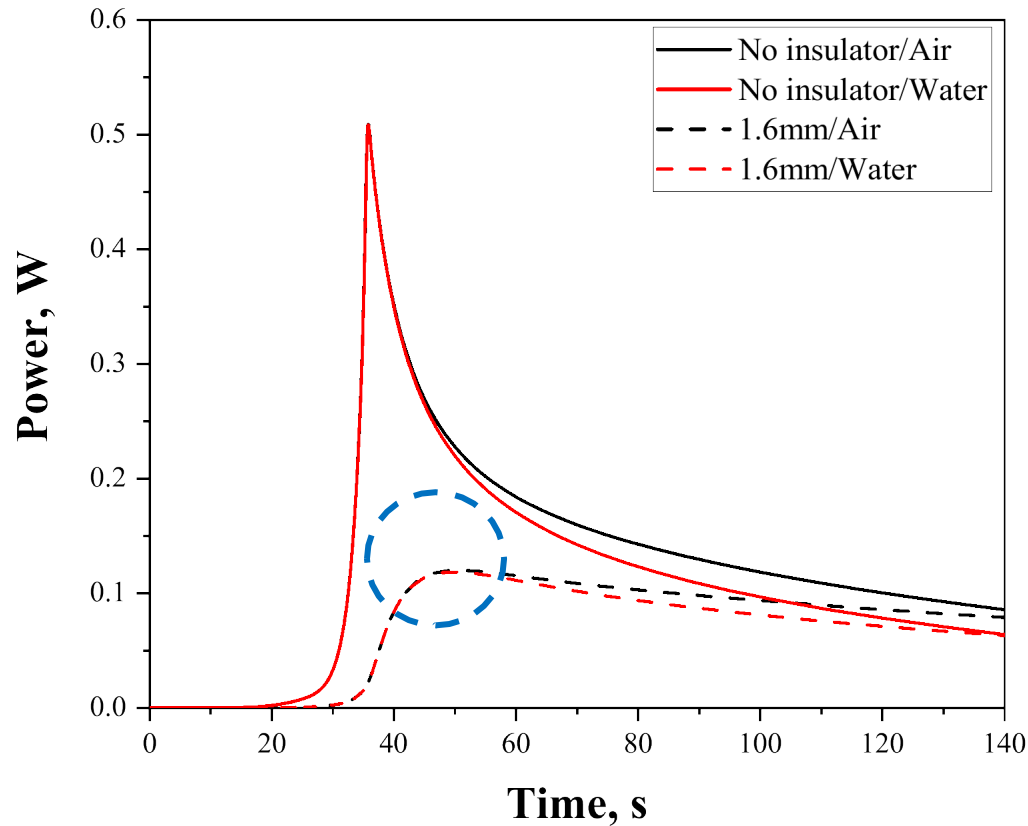
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Exploration of Mitigation Strategies Through Simulations

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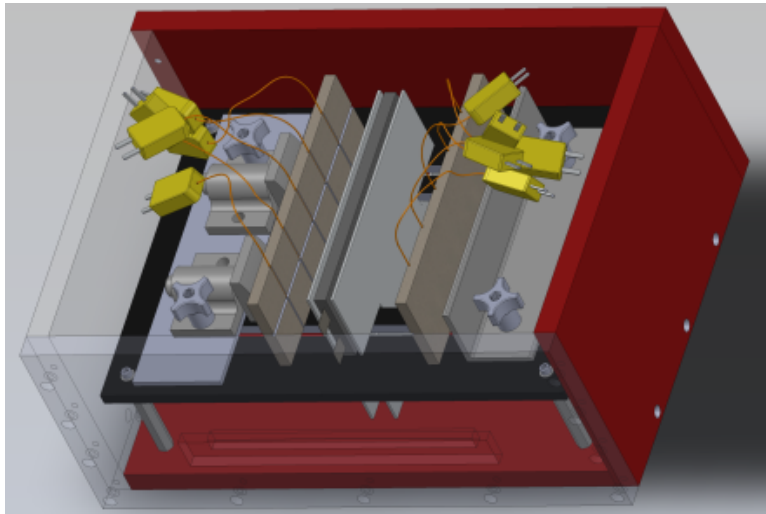
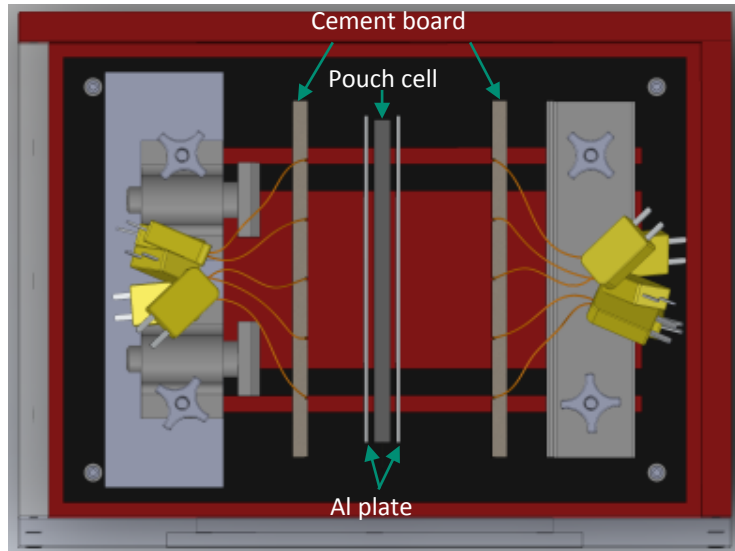
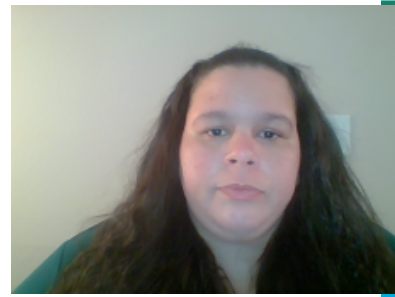


Effect of insulator thickness on the heat out of the battery pack

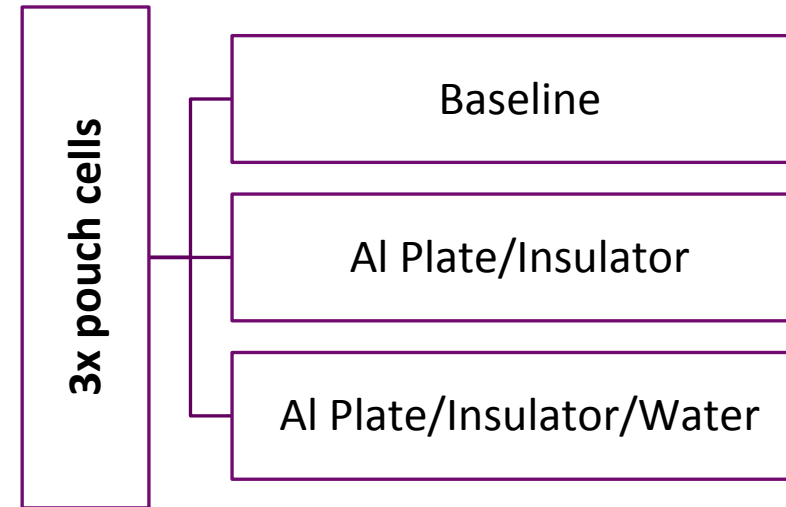


Insulation and structural materials delay heat transfer to adjacent cells/modules and allow for heat dissipation

Model Based Experimental Design

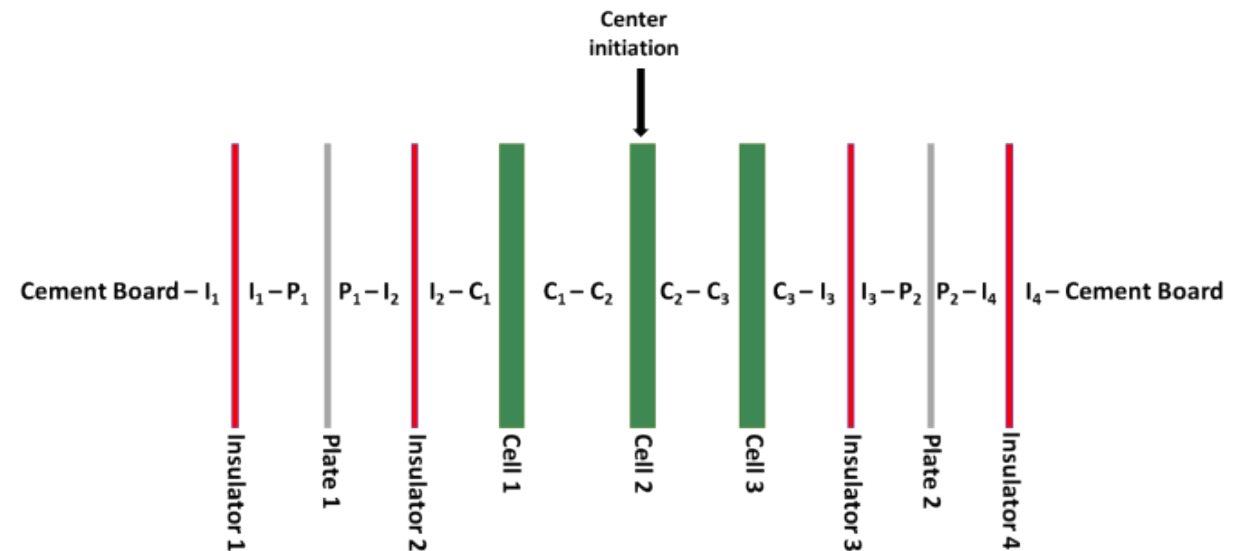


Test matrix



Al plate
0.8mm
G10 insulator
0.4mm or 1.6mm

Thermocouple map



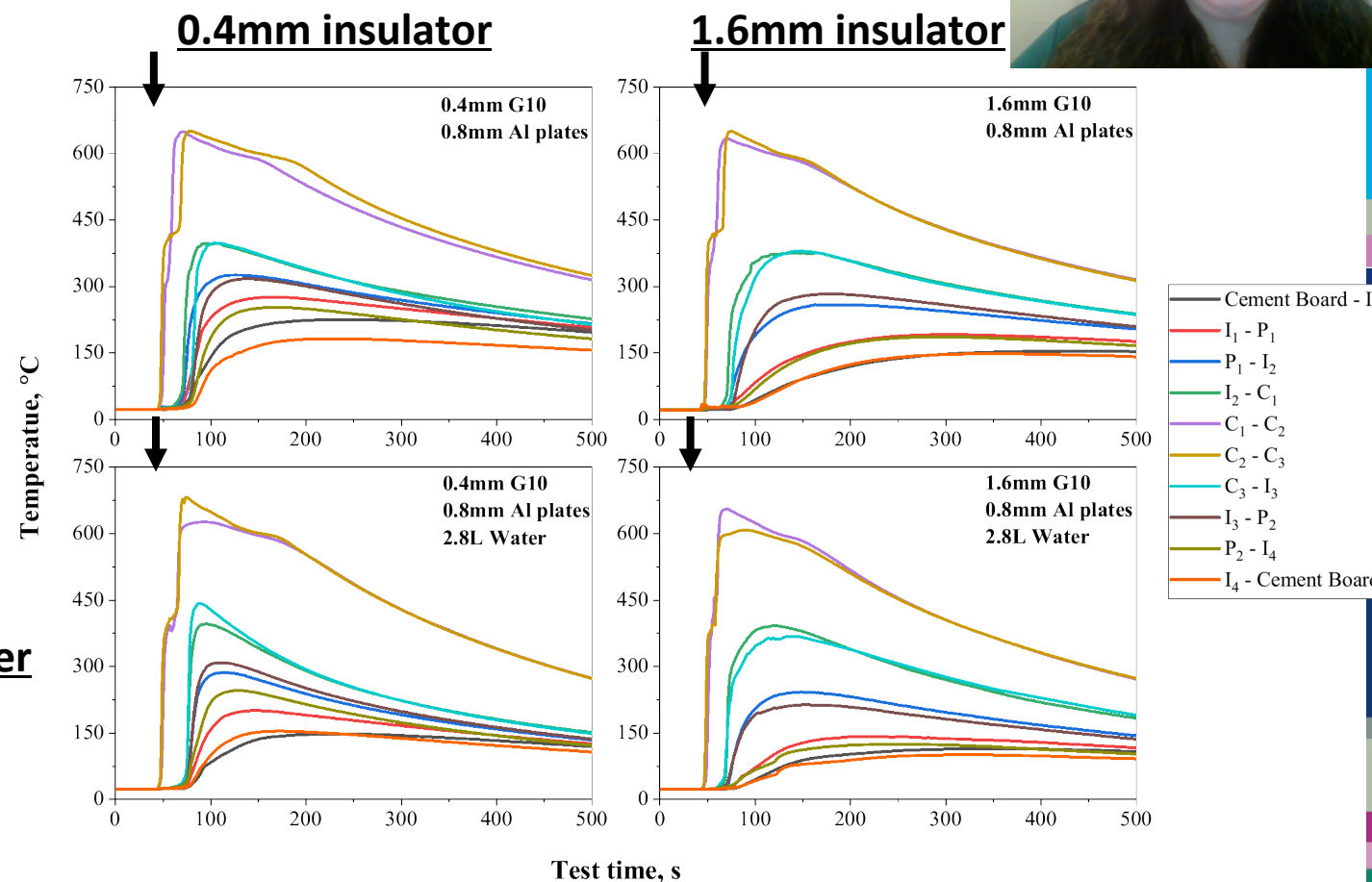
Temperature Profile



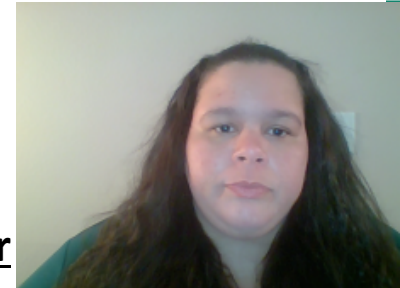
The maximum temperature of the failed cell remained in the same region independently of insulator thickness or level of cooling (air/water)

Plate

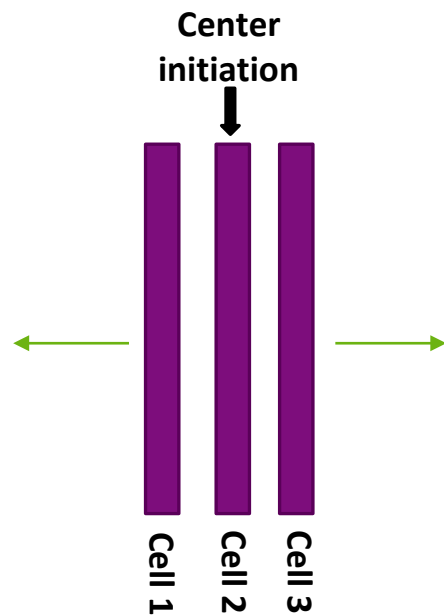
Plate/Water



Temperature Profile



No mitigation = heat transfer from the edge cell to the adjacent module sufficient to trigger thermal runaway

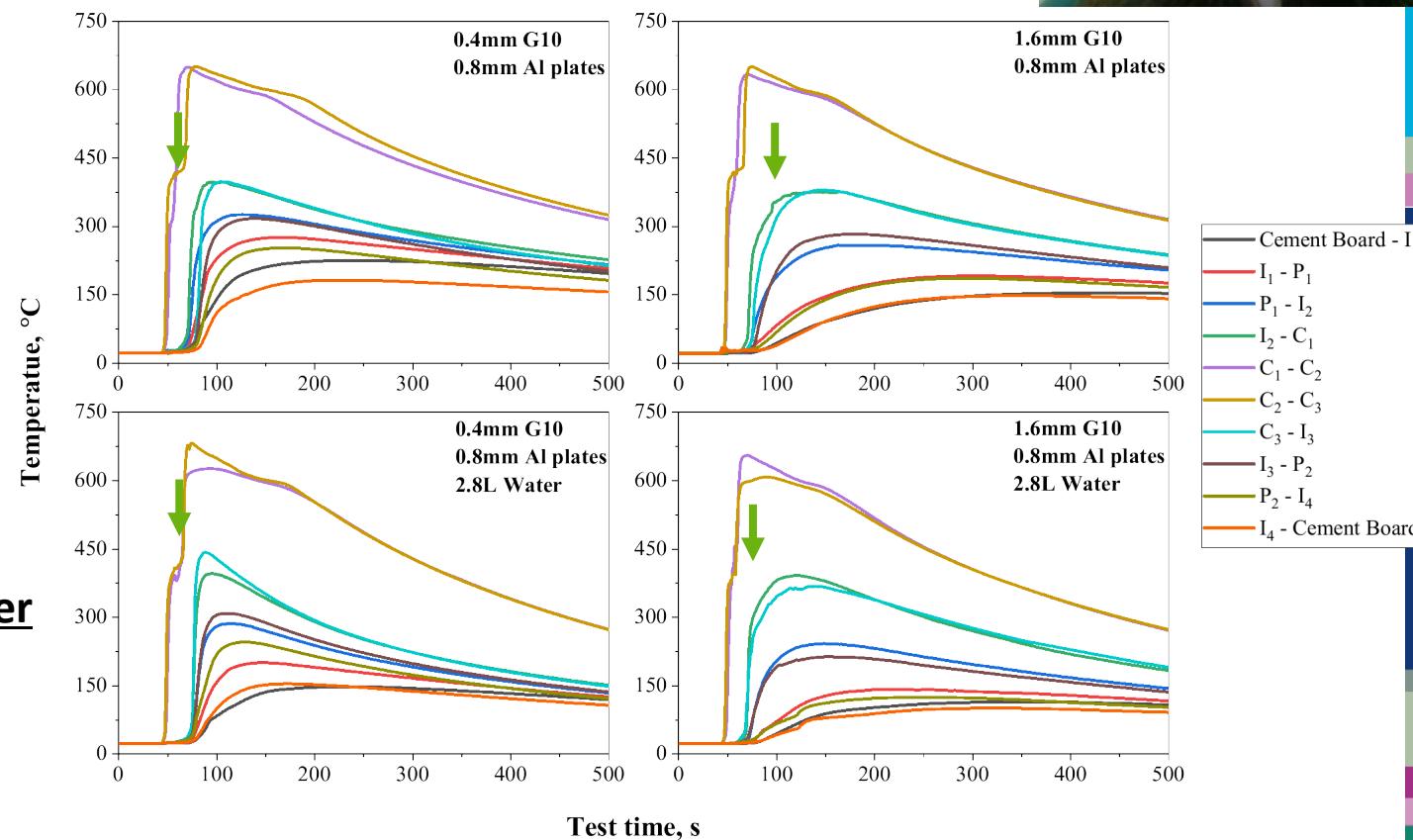


Plate

Plate/Water

0.4mm insulator

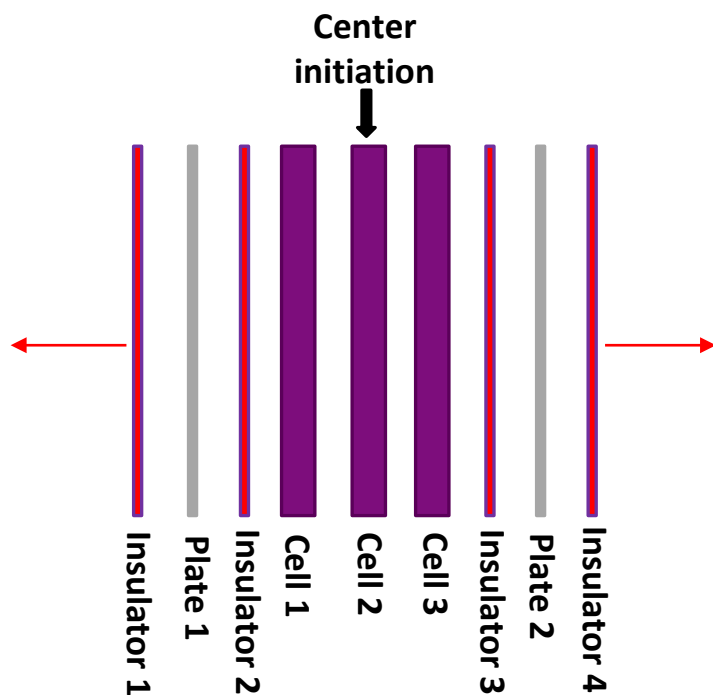
1.6mm insulator



Temperature Profile

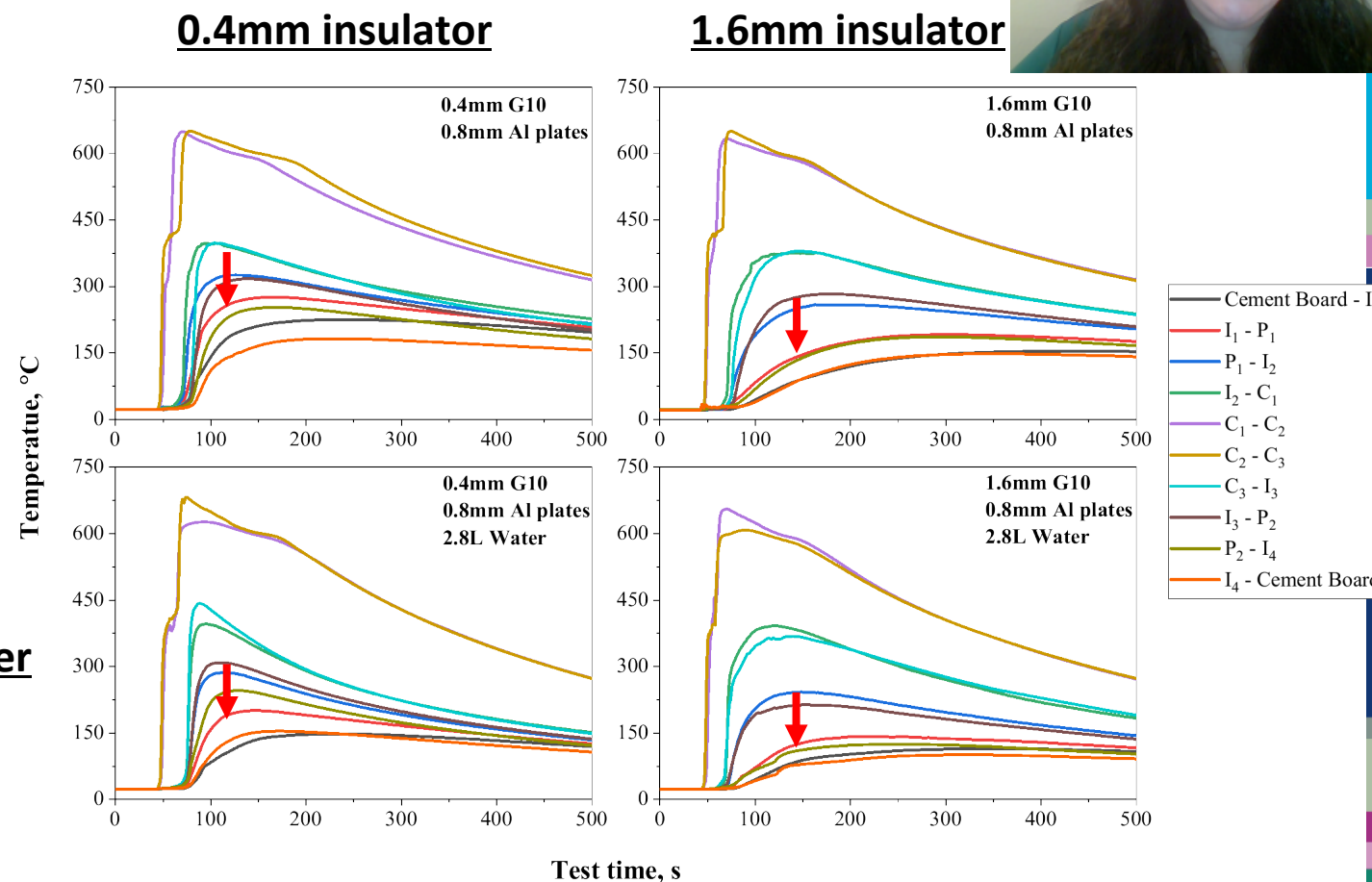


Mitigation = Adjacent module exposed to temperature between 100°C-150°C, reducing the risk of thermal propagation

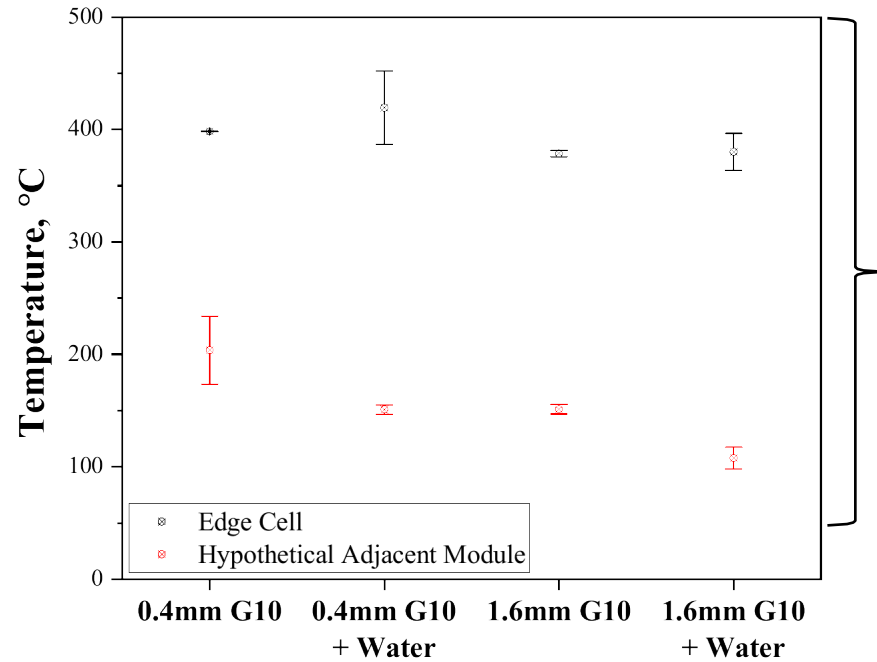


Plate

Plate/Water

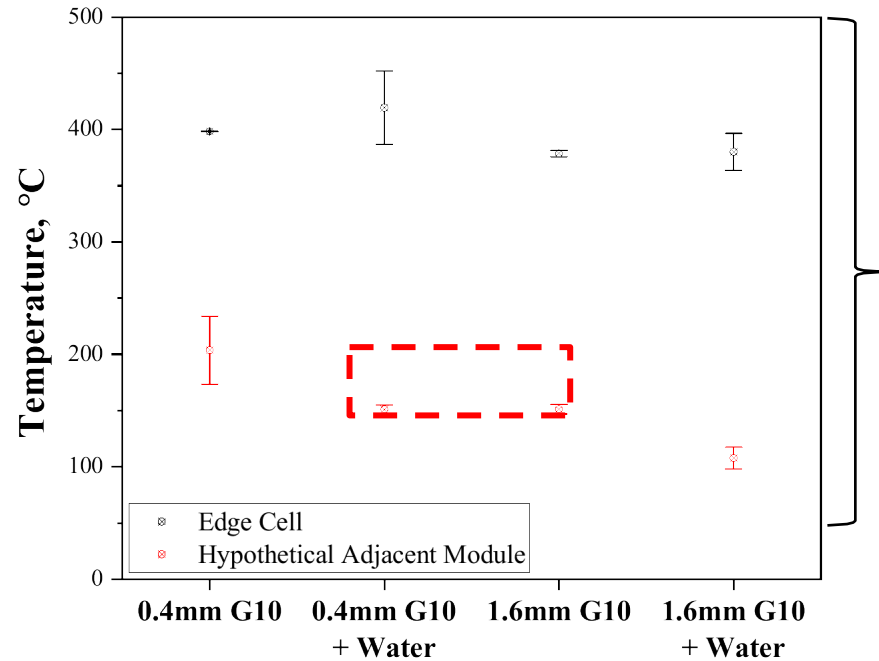
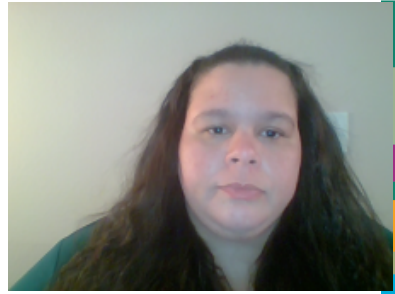


Hypothetical Adjacent Module Temperature Exposure



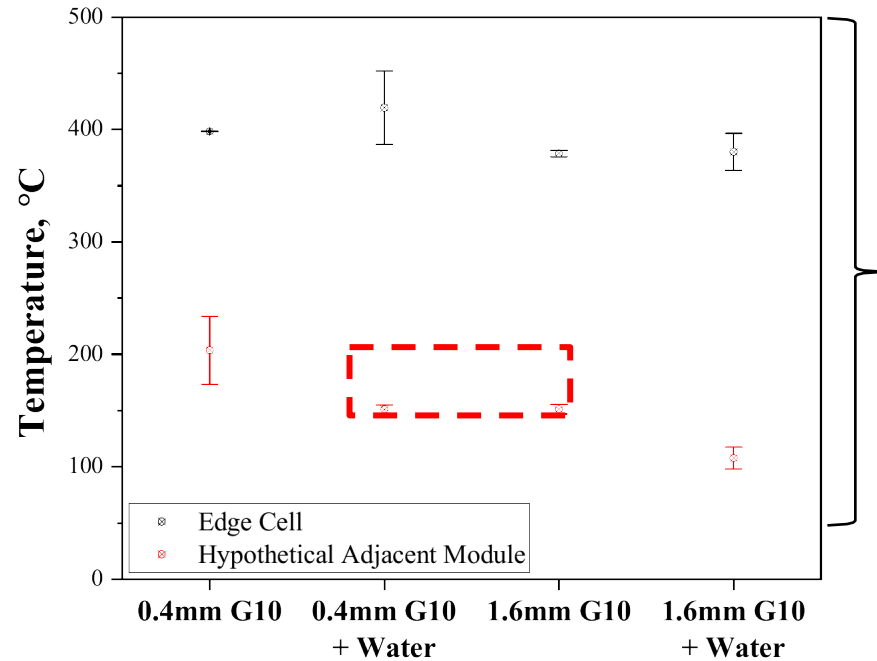
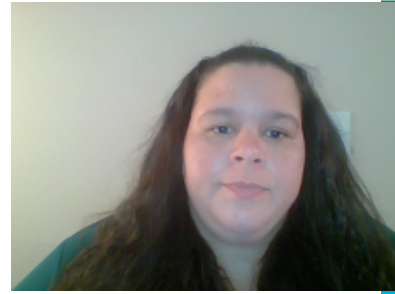
- The hypothetical adjacent module will be exposed to temperatures nearly identical when using 0.4mm G10 insulator with water-cooled plates or 1.6mm G10 insulator with no water
- Thicker insulators and the inclusion of water reduces the risk of failure propagation

Hypothetical Adjacent Module Temperature Exposure



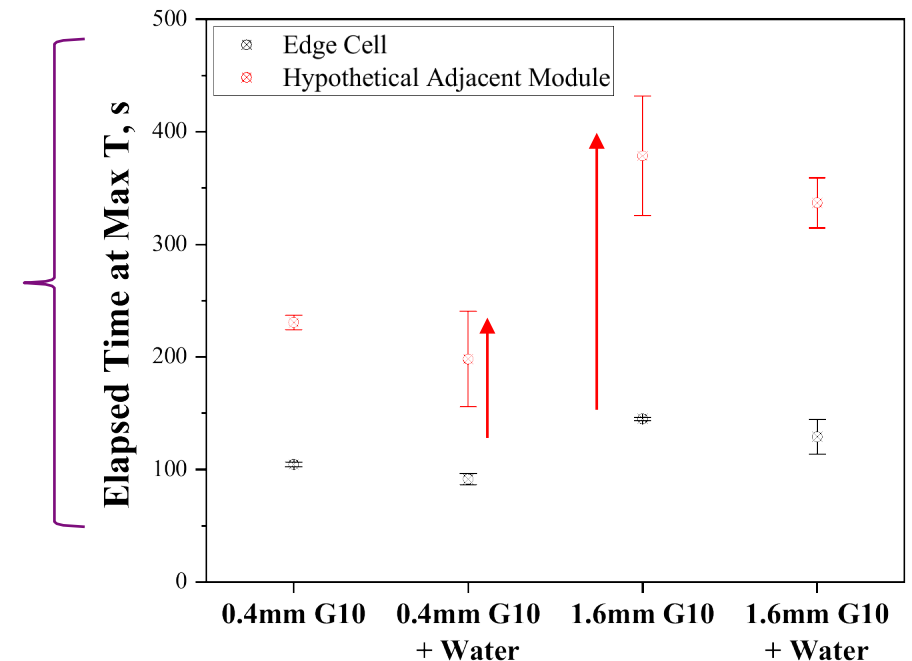
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Hypothetical Adjacent Module Temperature Exposure

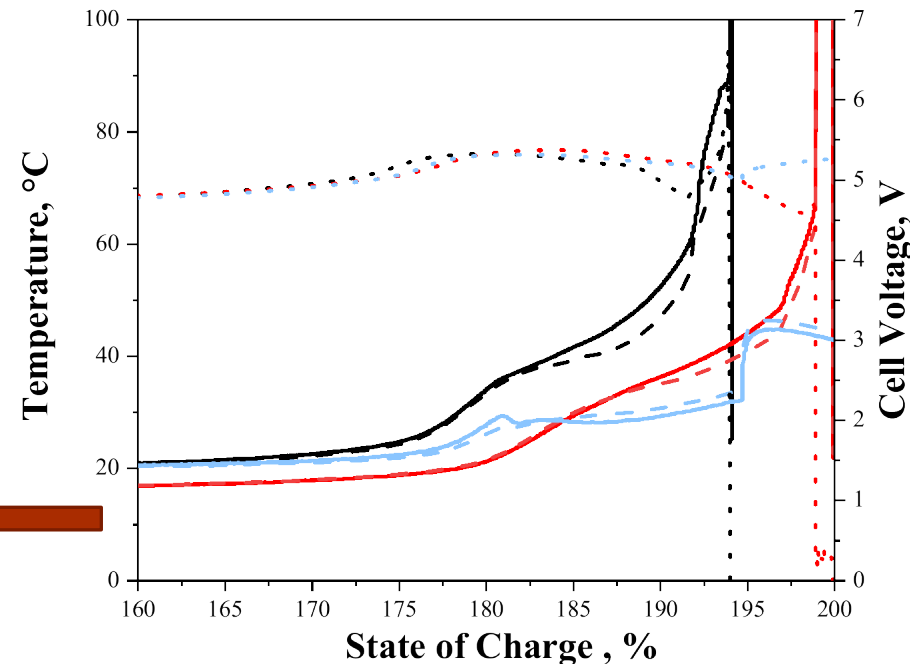
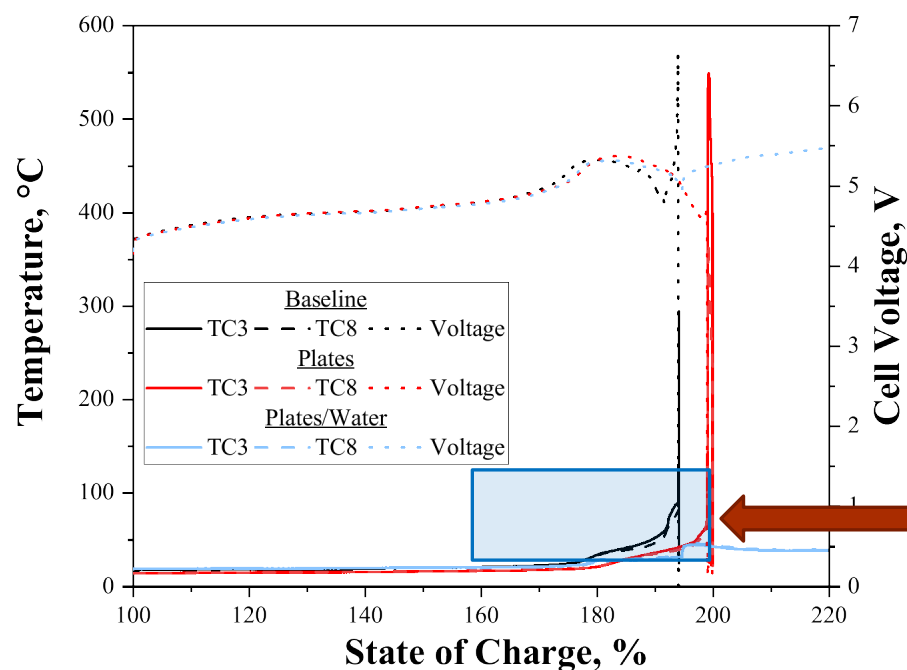
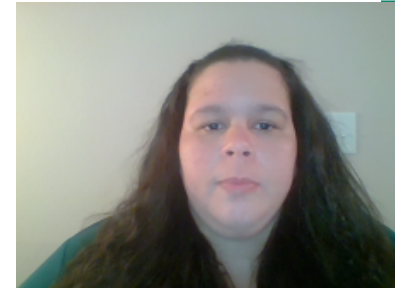


- The hypothetical adjacent module will be exposed to temperatures nearly identical when using 0.4mm G10 insulator with water-cooled plates or 1.6mm G10 insulator with no water
- Thicker insulators and the inclusion of water reduces the risk of failure propagation

The elapsed time at the max. temperature further demonstrates that adding thermal mass slows down the heat transfer to the hypothetical adjacent module



Overcharge Behavior with Air and Water Cooling

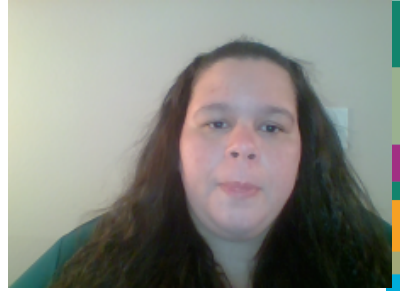


For SOC > 175%

- ✓ Baseline - faster self-heating and an earlier onset SOC to thermal runaway
- ✓ Plates - slower self-heating with maximum temperatures ~500°C
- ✓ Plates/Water - No thermal runaway

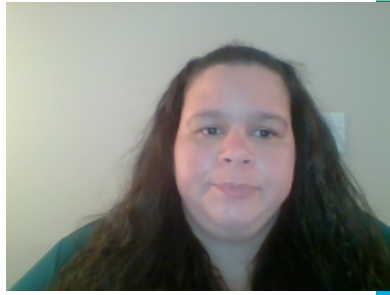


Summary



- A cell may exhibit a dramatically different failure response when in a string, module, or pack than during single-cell abuse testing
- Metallic plates are effective in small packs, but there is a trade-off between cost, weight, and volume
- Understanding of heat transfer is critical to incorporate the dynamics of heat transfer and make use of the system thermal mass
- Failure testing of large, complex systems is resources intensive. Model-based designs present a potential remedy to this, allowing us to infer a large amount of information from a relatively small number of tests.

Project Contacts



- Funded by the U.S. Department of Energy, Office of Electricity, Energy Storage program. Dr. Imre Gyuk, Program Director.
- Sandia National Laboratories is a multi-mission laboratory managed and operated by National Technology and Engineering Solutions of Sandia, LLC., a wholly owned subsidiary of Honeywell International, Inc., for the U.S. Department of Energy's National Nuclear Security Administration under contract DE-NA-0003525.

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